

# 1N4001W~1N4007W

Rev.E Sep.-2020

## 描述 / Descriptions

表面贴装整流二极管，反向电压：50V~1000V，正向电流：1.0A，薄型 SOD-123FL 封装。

Surface Mount General Purpose Silicon Rectifiers, Reverse Voltage: 50 to 1000V, Forward Current: 1.0A, SOD-123FL thin package.

## 特征 / Features

玻璃钝化芯片,适用于自动放置，铅符合欧盟 RoHS 指令 2011/65/EU，适用于表面贴装。无卤产品。

Glass Passivated Chip Junction, Ideal for automated placement, Lead free in comply with EU RoHS 2011/65/EU directives, For surface mounted applications. Halogen free product.

## 用途 / Applications

一般用途。

General purpose.

## 内部等效电路 / Equivalent Circuit

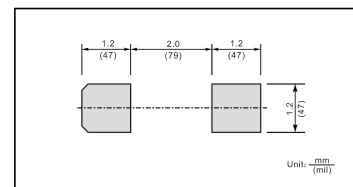


## 引脚排列 / Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



## 印章代码 / Marking

见印章说明。 See Marking Instructions.

**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating							单位 Unit
		1N4001W	1N4002W	1N4003W	1N4004W	1N4005W	1N4006W	1N4007W	
Maximum Recurrent Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at $T_a=65^\circ\text{C}$	$I_{F(AV)}$	1.0							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	$I_{FSM}$	30							A
Typical Junction Capacitance <sup>1)</sup>	$C_j$	8							pF
Typical Thermal Resistance <sup>2)</sup>	$R_{\theta JA}$	90							$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55~+150							$^\circ\text{C}$

Note:

1) Measured with  $I_F=0.5\text{A}$ ,  $I_R=1\text{A}$ ,  $I_{rr}=0.25\text{A}$ .

2) P.C.B. mounted with 0.2X0.2" (5X5mm) copper pad areas.

**电性能参数 / Electrical Characteristics(Ta=25°C)**

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating						单位 Unit
			1N4001W	1N4002W	1N4003W	1N4004W	1N4005W	1N4006W	
Maximum Instantaneous Forward Voltage	$V_F$	$I_F=1.0\text{A}$	1.1						V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	$I_R$	$T_a=25^\circ\text{C}$	5.0						$\mu\text{A}$
		$T_a=125^\circ\text{C}$	50						$\mu\text{A}$

电参数曲线图 / Electrical Characteristic Curve

Fig.1 Forward Current Derating Curve

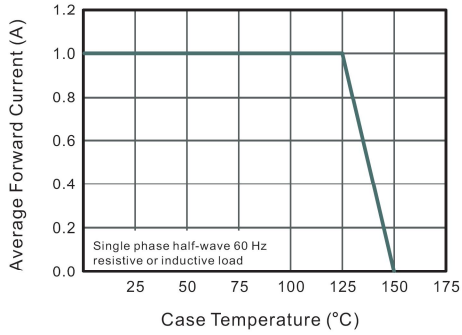


Fig.2 Typical Instaneous Reverse Characteristics

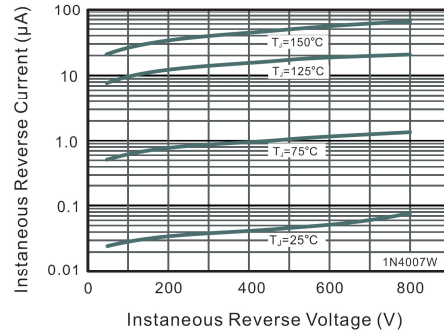


Fig.3 Typical Forward Characteristic

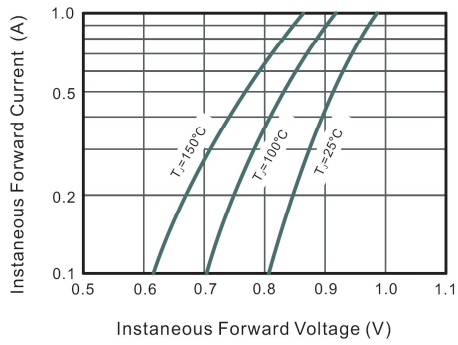


Fig.4 Typical Junction Capacitance

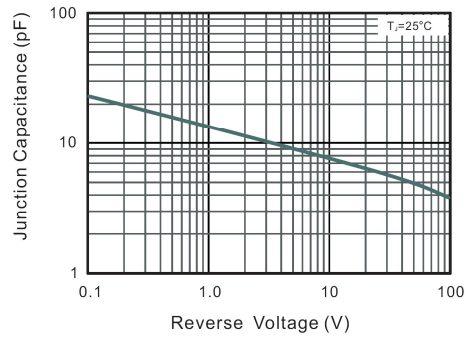
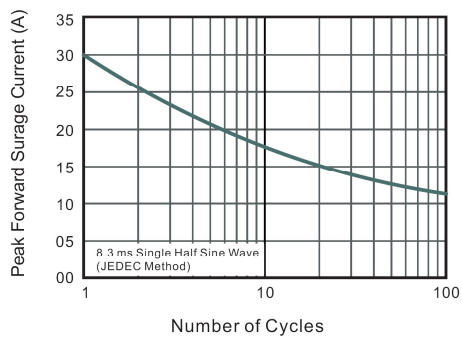
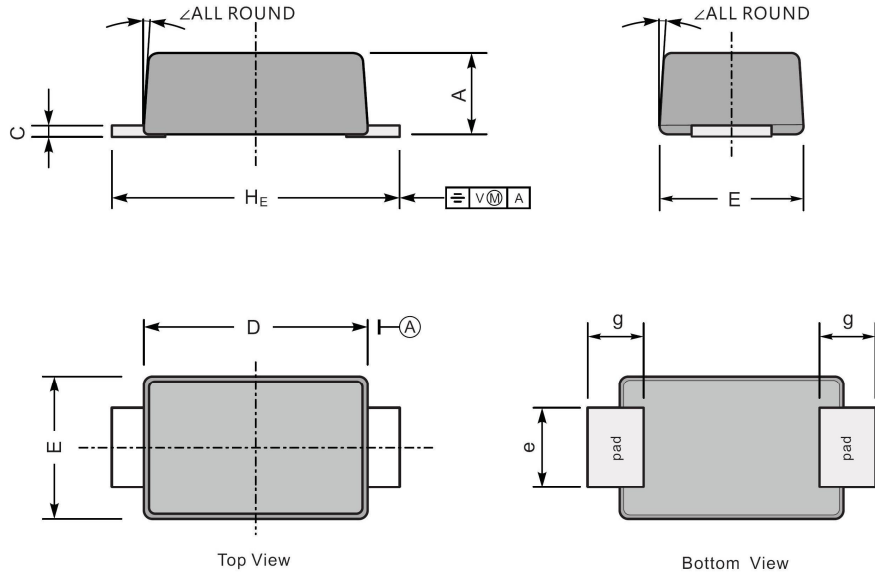


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



外形尺寸图 / Package Dimensions

SOD-123FL

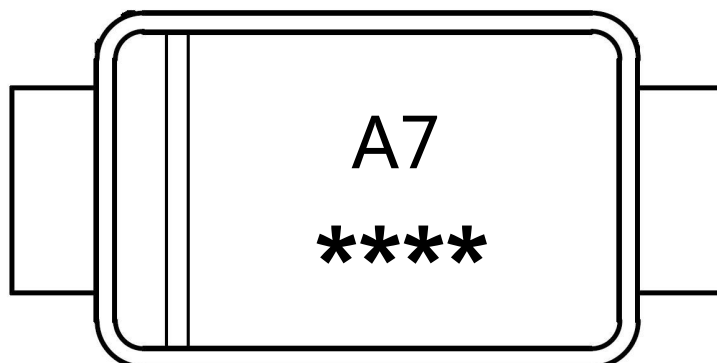


UNIT		A	C	D	E	e	g	H <sub>E</sub>	∠
mm	max	1.1	0.20	2.9	1.9	1.1	0.9	3.8	7°
	min	0.9	0.12	2.6	1.7	0.8	0.7	3.5	
mil	max	43	7.9	114	75	43	35	150	
	min	35	4.7	102	67	31	28	138	

## Marking

Type number	Marking code
1N4001W	A1
1N4002W	A2
1N4003W	A3
1N4004W	A4
1N4005W	A5
1N4006W	A6
1N4007W	A7

印章说明 / Marking Instructions



说明：

A7： 为型号代码

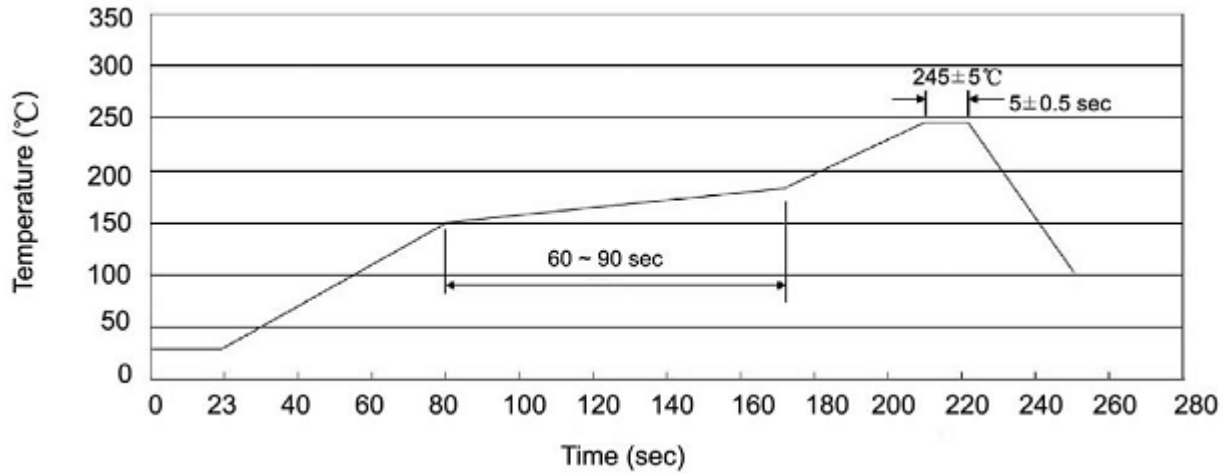
\*\*\*\*： 为生产批号追溯码，第1个\*为年月代码，后面3个\*为当月小批号代码

Note:

A7： Product Type Code

\*\*\*\*： Lot No. Code ,The 1st \* means:YM Code ,The last 3 \* means:little Lot No Code

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-123FL	3000	8	24000	5	120000	7" ×11	185X180X105	390X385X205

**使用说明 / Notices**